PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DAE SUB JUNG	04/25/2018
DE YAN CHEN	04/25/2018
GUANG LI YANG	04/25/2018

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANGJIANG ROAD
Internal Address:	PUDONG NEW AREA
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State/Country:	CHINA
Postal Code:	201203
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Street Address:	18 WENCHANG ROAD, BEIJING ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA
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State/Country:	CHINA
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16794757

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	SMIC00129-1D US

NAME OF SUBMITTER:	YI-MING TSENG
SIGNATURE:	/Yi-Ming Tseng/
DATE SIGNED:	02/20/2020
Total Attachments: 2 source=SMIC00129US_Assignment_EF#page1.tif source=SMIC00129US_Assignment_EF#page2.tif	

CLIENT REFERENCE NO.: 2016-00815-SH-US
ATTORNEY DOCKET NO.: SMIC00129 US

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I

Dae Sub JUNG of 18 Zhangjiang Road
Pudong New Area
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hereby sell, assign and transfer to **Semiconductor Manufacturing International (Shanghai) Corporation**, having a place of business at 18 Zhangjiang Road, Pudong New Area, Shanghai, P.R.C. 201203, and, **Semiconductor Manufacturing International (Beijing) Corporation**, having a place of business at 18 Wenchang Road, Beijing Economic-Technological Development Area, Beijing, China, 100176, its successors and assigns, the entire right, title and interest throughout the world in the invention entitled

A SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisionals, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this ~~4~~25 day of Apr., 2018.

Dae Sub Jung
Dae Sub JUNG

WITNESSED: 马燕春

Signature 马燕春

Date 2018.04.25

Type or print name of witness

Executed this 25 day of Apr., 2018.

De Yan CHEN

WITNESSED: 马燕春

Signature 马燕春

Date 2018.04.25

Type or print name of witness

Executed this 25 day of Apr., 2018.

Guang Li YANG

WITNESSED: 马燕春

Signature 马燕春

Date 2018.04.25

Type or print name of witness